

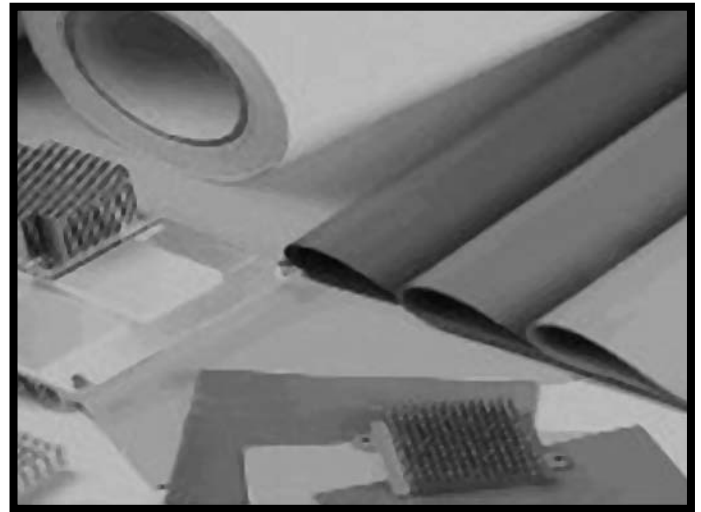
Thermal Management Materials (6000 Series) 6004 Material

Product Summary

MAJR 6000 thermal Management materials consist of sheet, adhesive, and grease compounds; these thermal materials are used in a wide variety of markets such as chip sets for IC controller packages, IT for industrial and personal computers, DRAM Modules, telecom devices, automotive control units, and a variety of other products used in military and commercial markets.

Product Application (6004)

This material exhibits very high thermal conductivity. In addition, this material exhibits high compressibility and natural adhesiveness. It is excellent for applications where electrical insulation and thermal conductivity is needed. The exceptional ability of this material to conduct heat away from sensitive components makes it applicable for use in very heat sensitive applications. The 6004 is an excellent high-level thermal conductive interface material.

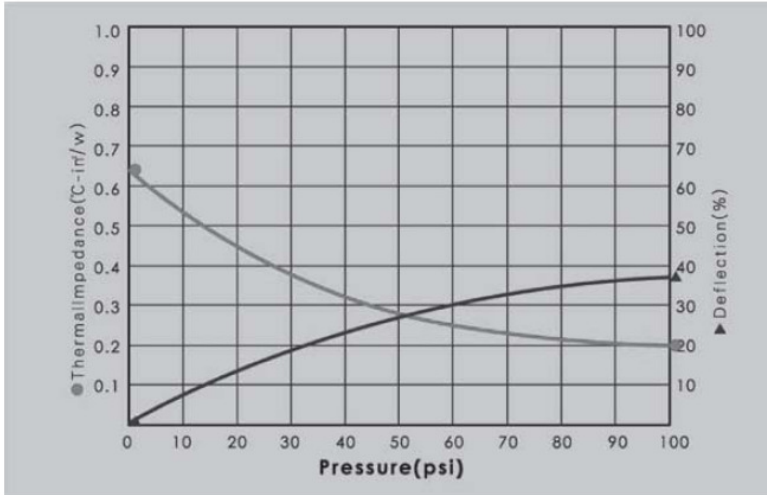


Product Technical Data (6004)

PROPERTY Material 6004	RANGE	UNIT	TEST METHOD
Color	Dark Gray	—————	Visual
Thickness	0.13 - 15	mm	ASTM D374
Specific Gravity	2.28 +/-0.2	g/cm ³	ASTM D792
Hardness	20 +/-5	Shore A	ASTM D2240
Elongation	130 +/-13	%	ASTM D412
Tensile Strength	8 +/-2	Kgf/cm ²	ASTM D412
Weight Loss	<1	%	@204°C/24 hr.
Dielectric Breakdown (V)	>7.0	KV	ASTM D149
Surface Resistance	10 ¹⁷	Ohm	ASTM D257
Temperature Continuous	-50 to +220	°C	-
Flame Rating	94V-0	UL	UL
Thermal Conductivity	3.2	W/m-k	ASTM D5470

Thermal Management Materials (6000 Series) 6004 Material (Cont.)

Test Sample Thickness: 1.5mm



Thermal Resistance vs. Pressure (Gray)

The 6004 material provides low thermal impedance; with increasing pressure, thermal impedance becomes lower.

Deflection vs. Pressure (Black)

The 6004 material, exhibits high deflection (softness); as pressure increases the deflection percentage increases. This material provides good compliance to mating surfaces.